
Change notice of package name of DFN(PLP) package

Dear our valuable customer,

Thank you for your continued support.

We are writing to announce package name of DFN(PLP) package will be changed because of the review of the package name due to the establishment of Nisshinbo Micro Devices Inc. Please refer to the following information for details.

1. Target products

DFN(PLP) package products*

* DFN(PLP)xxxx-xy

x: Numbers, y: Letters, <e.g.> DFN(PLP)1010-4B

You can check the package list from the following URL.

<https://www.nisshinbo-microdevices.co.jp/en/design-support/package/>

2. Changes

· Current Package name: DFN(PLP)

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· New Package Name: DFN(PL)

<e.g.> DFN(PLP)1010-4B → DFN(PL)1010-4B

3. Schedule

From February 2023

4. Notes

- Package specifications between current DFN(PLP) and new DFN(PL) are same. (NO change)
- All following items will NOT be changed.
 - Product name
 - ICs including Electrical characteristics, Dimensions, Materials, Factory, Process and Method.
 - Packing specifications including Product labels.

Please let us know if you have any questions or concerns.

Thank you for your understanding and cooperation.

Respectfully Yours,


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Hiroyuki Sugiura
General Manager
Sales & Marketing Division
Electronic Devices Business Headquarters
Nisshinbo Micro Devices Inc.